



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS

)  
Examiner: Phat X. CAO

Application No.: 10/632,549

)  
Group Art Unit: 2814

Filed: August 2, 2003

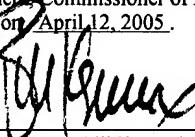
)  
Date: April 12, 2005

Title: Semiconductor multi-package module  
having wire bond interconnect between  
stacked packages

)  
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on April 12, 2005.

Signed

  
Bill Kennedy

MAIL STOP AMENDMENT  
COMMISSIONER FOR PATENTS  
P.O Box 1450  
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

Applicant responds as follows to the Office action mailed October 12, 2004.

**Amendments to the Specification** begin on page 2 of this paper.

Amendments to the claims are reflected in the **Listing of Claims** which begins on page 3 of this paper.

**Remarks** begin on page 5 of this paper.